



SOT1046-1

plastic thermal enhanced extremely thin quad flat package;
no leads; 16 terminals; UTLP based

5 March 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HXQFN16U
Package type industry code	HXQFN16U
Package style descriptive code	HXQFN (thermal enhanced extremely thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	01-12-2007
Manufacturer package code	SOT1046

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.9	2	2.1	mm
package width	1.9	2	2.1	mm
seated height	-	0.5	-	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	16	-	



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2 Package outline

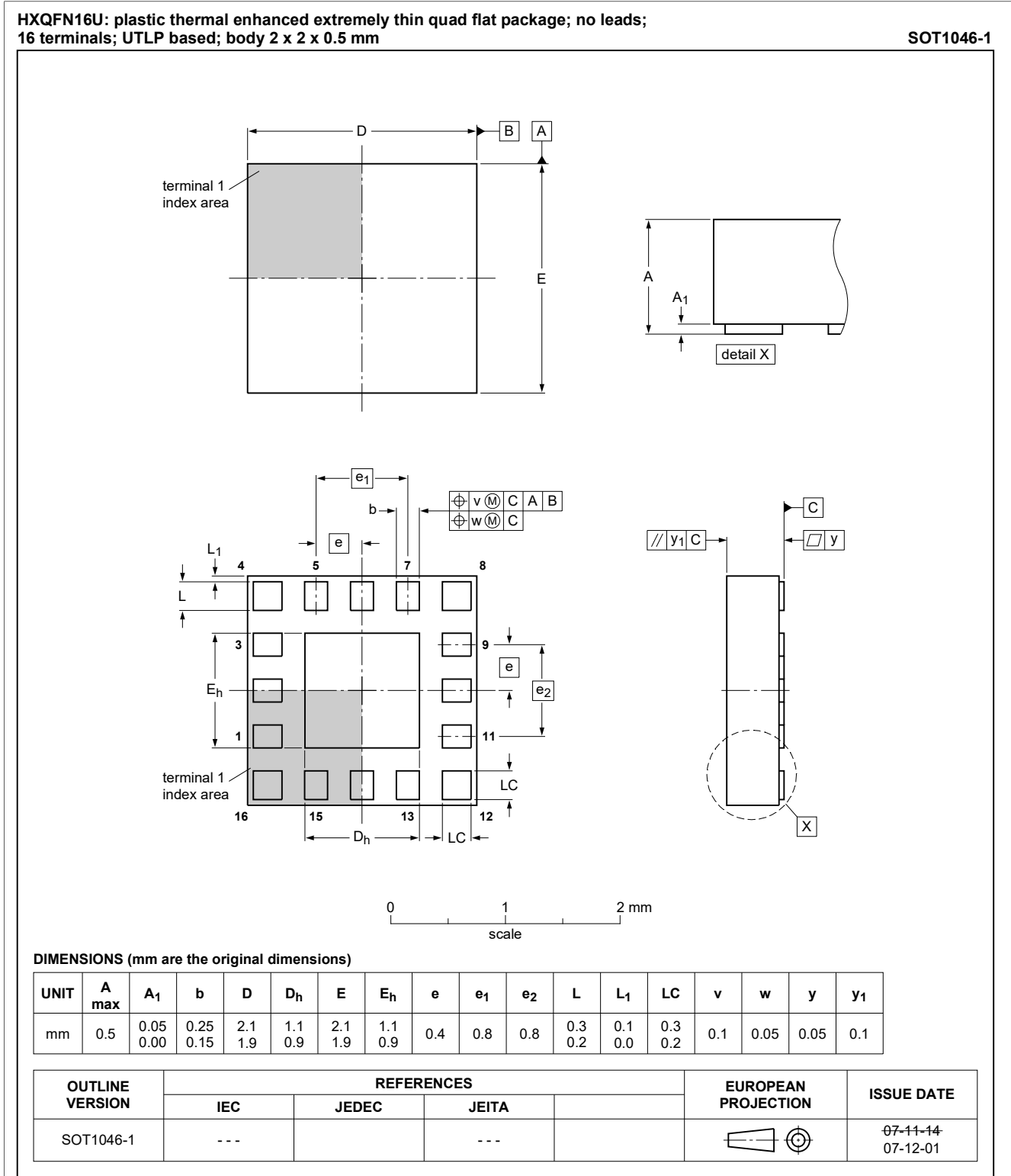


Figure 1. Package outline HXQFN16U (SOT1046-1)

3 Soldering

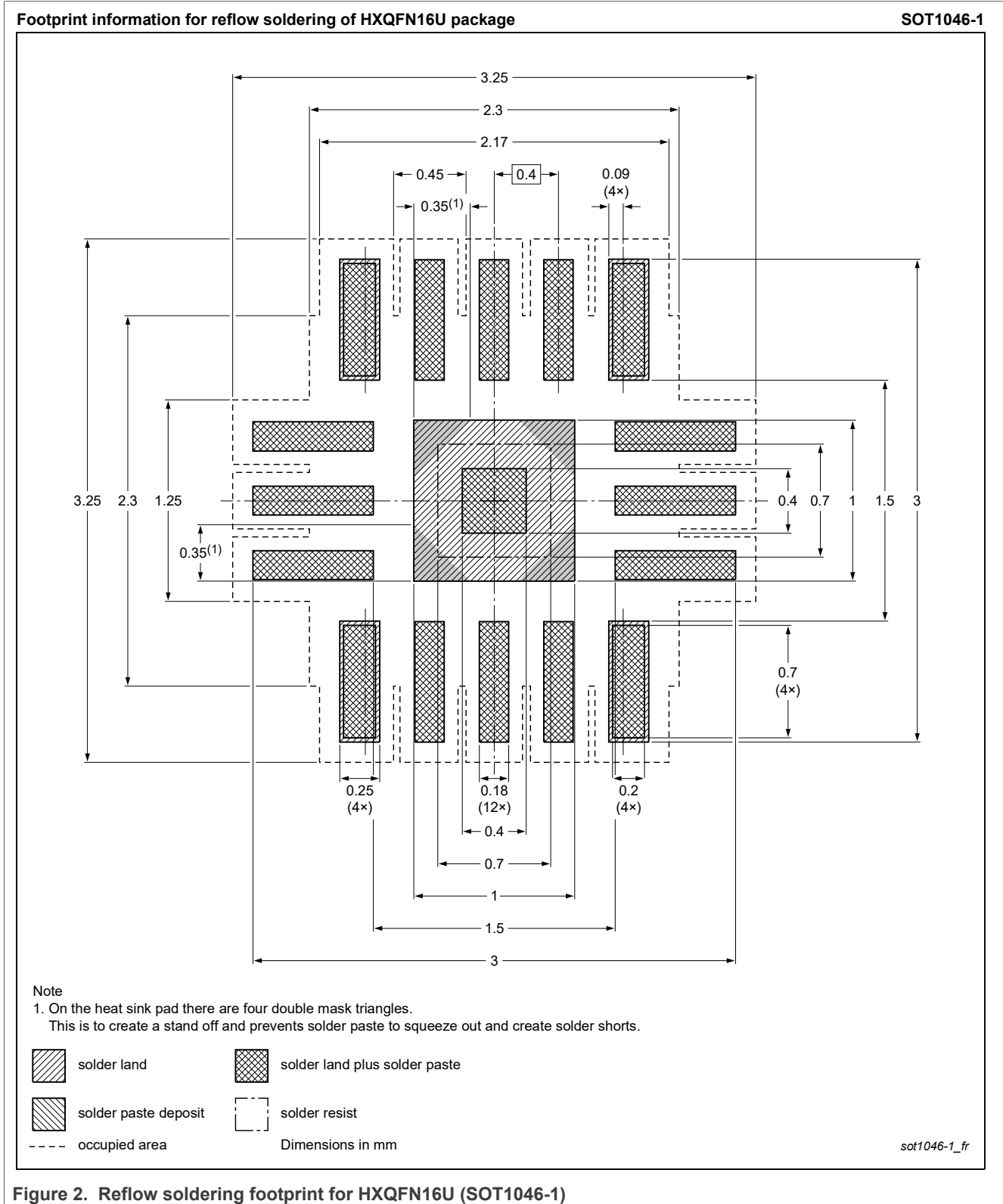


Figure 2. Reflow soldering footprint for HXQFN16U (SOT1046-1)

4 Legal information

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Contents

1 Package summary1
2 Package outline2
3 Soldering3
4 Legal information4